

CBR02C229B1GAC

CBR-SMD RF COG, Ceramic, 2.2 pF, +/-0.1 pF, 100 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0201



Click here for the 3D model.

Dimensions	
Chip Size	0201
L	0.6mm +/-0.03mm
W	0.3mm +/-0.03mm
Т	0.3mm +/-0.03mm
В	0.15mm +/-0.05mm

Packaging Specifications		
Packaging	T&R, 180mm, Plastic Tape	
Packaging Quantity	15000	

General Information			
Series	CBR-SMD RF COG		
Style	SMD Chip		
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I		
Features	Ultra High Q, Low ESR, Class I		
RoHS	Yes		
Termination	Tin		
Marking	No		
AEC-Q200	No		
Component Weight	0.3 mg		
Notes	Solder Wave or Solder Reflow.		
Shelf Life	78 Weeks		
MSL	1		

Specifications			
Capacitance	2.2 pF		
Capacitance Tolerance	+/-0.1 pF		
Voltage DC	100 VDC		
Dielectric Withstanding Voltage	250 VDC		
Temperature Range	-55/+125°C		
Temperature Coefficient	COG		
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms		
Dissipation Factor	0.2%1MHz 1.0Vrms		
Aging Rate	0% Loss/Decade Hour		
Insulation Resistance	10 GOhms		
Quality Factor	444		

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.